# **SPEAr1310** embedded microprocessor



#### **STMicroelectronics**

### Dual ARM<sup>®</sup> Cortex<sup>®</sup>-A9 cores enable high-performance, high-connectivity and industrial applications

ST's SPEAr1310 is a part of the growing SPEAr family of embedded MPUs for networking.

It offers an unprecedented combination of processing performance and extreme power reduction control for next-generation communication applications.

The SPEAr1310 is based on ARM's new multicore technology (Cortex-A9 SMP/AMP), and is manufactured using ST's 55 nm **HCMOS** 

low-power silicon process.



#### **Key features**

- CPU subsystem
  - Dual ARM Cortex-A9 cores. 600 MHz
  - Supports both symmetric (SMP) and asymmetric (AMP) multiprocessing
  - 32 + 32-Kbyte L1 instruction/data cache per core with parity check
  - Shared 512-Kbyte L2 cache (ECC protected)
  - Accelerator coherence port
- Bus: 64-bit multilayer network-onchip
- Memories
  - 32 Kbyte boot ROM
  - 32 Kbyte internal SRAM
  - Multiport controller (MPMC) for external DDR2-800/DDR3-1066
  - Controller (FSMC) for external Flash and SRAM
  - Controller (SMI) for external serial NOR Flash

- Controls external peripherals
  - TFT LCD display up to 1920 x 1080 (60 Hz)
  - Touchscreen I/F
  - 9 x 9 keyboard
- Memory card interface
- Connectivity
  - Giga/Fast Ethernet ports
  - 3x PCle 2.0 / SATA
  - 3x USB 2.0 (Host/OTG)
  - 2x CAN 2.0 a/b interfaces
  - 2x HDLC RS485
  - I<sup>2</sup>S, UART, I<sup>2</sup>C and SPI
- Expansion interface (EXPI)
- Security: C3 cryptographic accelerator
- Power saving
  - Power islands for leakage reduction
  - IP clock gating for dynamic power reduction
  - Dynamic frequency scaling
- Package: PBGA628 (23 x 23 mm, 0.8 mm pitch)

## Overview

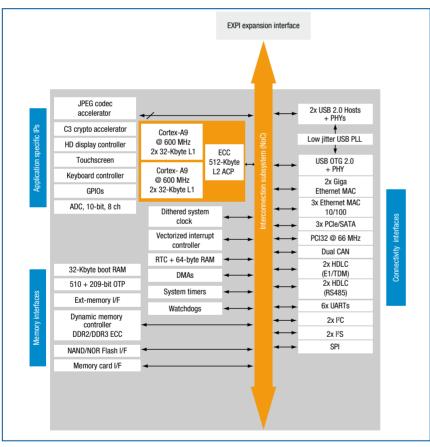
The SPEAr1310 combines two ARM Cortex-A9 cores with a DDR3 (third-generation, double-data-rate) memory interface. Together with ST's low-power 55 nm HCMOS process technology, the SPEAr1310 delivers high computing power and customizability for a variety of embedded applications, with a high degree of cost competitiveness. The dual processors support both fully symmetric and asymmetric operations, at speeds of 600 MHz (industrial worst-case conditions) for an equivalent of 3000 DMIPS.

In addition to unrivalled low power and multiprocessing capabilities, this new eMPU offers the innovative network-on-chip (NoC) technology. NoC is a flexible communications architecture that enables multiple and different traffic profiles while maximizing data throughput in the most performance and power-efficient way.

Equipped with an integrated DDR2/DDR3 memory controller and a full set of connectivity peripherals, including USB, SATA, PCIe (with integrated PHY) and Giga Ethernet MAC, the SPEAr1310 targets high-performance, embedded-control applications across the communication, computer peripherals and industrial automation markets.

Cache memory coherency with hardware accelerators and I/O blocks increases throughput and simplifies software development. The accelerator coherency port (ACP), together with the device's NoC routing capabilities, addresses the latest application requirements for hardware acceleration and I/O performance. ECC (error correction coding) protection against soft and hard errors on both DRAM and L2 cache memories significantly improves the mean-time-between-failures for enhanced reliability.

#### SPEAr1310 block diagram



#### **Design support**

Information on development tools and evaluation boards, as well as downloads of the latest STLinux OS, firmware, and technical documentation, can be found on:

www.st.com/spear





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